

ABSTRACT

BONDHEAD FOR WIRE BONDING APPARATUS

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A bondhead is provided that comprises a bondhead body for holding a bonding tool, such as an ultrasonic transducer, and a bondhead actuator coupled to the bondhead body for moving the bonding tool with respect to a bonding surface. A wire clamping device, which may comprise a wire clamp holder and a wire clamp, is movable relative to the bondhead body for feeding a bonding wire to the bonding tool. A wire clamping device actuator is operative to move the wire clamping device relative to the bondhead body for improved control of the feeding of bonding wire to the bonding tool.

15 (Figure 2)